

DECLARATION AND PETITION

As the below named inventors, we hereby declare that:

Our residences, post office addresses and citizenships are as stated below next to our names.

We believe that we are an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR FORMING MICROELECTRONIC SPRING STRUCTURES ON A SUBSTRATE, the specification of which is attached hereto.

We hereby state that we have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

We acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

We hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: None

PRIOR FOREIGN APPLICATION(S)

				Priority claimed	
Number	Country	Date Filed	Yes	No	
				Priority claimed	
Number	Country	Date Filed	Yes	No	

We hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below: None

Application Serial No.	Filing Date
Application Serial No.	Filing Date

We hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, we acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

<u>09/710,539</u>	<u>November 9, 2000</u>
Application Serial No.	Filing Date
<u>09/364,788</u>	<u>July 30, 1999</u>
Application Serial No.	Filing Date

We hereby declare that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Correspondence should be addressed to:

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Wherefore we pray that Letters Patent be granted to us for the invention or discovery described and claimed in the foregoing specification and claims, and we hereby subscribe our names to the foregoing specification and claims, declaration and petition.

Full name of first inventor: BENJAMIN N. ELDRIDGE

Inventor's signature: _____

Date: _____

Residence: 651 Sheri Lane, Danville, CA 94526

Citizenship: U.S.A.

Post Office Address: Same as above

